APPLICA	BLE STAN	IDARD										
	Operating temperature ra	nge	-55°C to 85°C			erature			10℃ TO 50℃(packed	cond	ition)	
RATING	Voltage		30V AC/DC			ating or dity ran	storage ge	Relative humidity 90%MAX(n			not dewed)	
	Current		0.20A		Appli	cable ca	able		t=0.2±0.02mm, gold p	lating	3	
		"	SPEC	IFICA	TIOI	NS						
IT	EM		TEST METHOD				RE	QUI	REMENTS	QT	АТ	
CONSTR	UCTION					I						
General exar	mination	Visually a	and by measuring instrumen	ıt.		Accord	ling to draw	ving.		×	×	
Marking		Confirme	d visually.			(note 1,2)				×	×	
ELECTRI	CAL CHA	RACTE	RISTICS									
Voltage proo	f	90V AC fo	or 1 min.			No flas	shover or br	reak	down.	×	×	
Insulation resistance		100V DC.	100V DC.			50ΜΩ	MIN.			×	×	
Contact resistance		20mV AC MAX, 1mA.				2 MAX.	-C h	ulk registeres (I. Omm)	×	×		
MECHAN	IICAL CHA	│ NDACTE	DISTICS			includi	ng FPC, FF	-C b	ulk resistance (L=8mm)			
			ry 10 to 55 Hz, half amplitud	le 0.75 mn	n.					×	Τ_	
Vibration		for 10 cycles in 3 axial directions.			① No electrical discontinuity of 1µs.				Ĺ			
Shock		981 m/s ² , duration of pulse 6 ms at 3 times					② Contact resistance: 300mΩ MAX.③ No damage, crack and loose parts.				_	
			in 3 both axial directions.						: 300mΩ MAX.	~	<u> </u>	
Mechanical c	peration	10 times i	insertions and extractions.						and loose parts.	×		
FPC retention	n force		Measured by applicable FPC. (thickness of FPC shall be t=0.20mm at initial ondition)			Direction of insertion: (0.14 × n)+1N MIN(<i>note 3</i>) (n: Number of contacts)			×	-		
ENVIRO	MENTAL	CHARA	ACTERISTICS			11 -				ı		
Corrosion salt mist Ex		Exposed	Exposed at 35±2°C, 5% salt water spray for 96h.			 Contact resistance: 300mΩ MAX. No damage, crack and loose parts. No evidence of corrosion which affects connector's operation. 				×		
Rapid change of temperature		Temperature-55 \rightarrow +15To+35 \rightarrow +85 \rightarrow +15To+35°C Time 30 \rightarrow 2 To 3 \rightarrow 30 \rightarrow 2 To 3 min Under 5 cycles.			① Contact resistance: 300mΩ MAX. ② Insulation resistance: 50MΩ MIN.				×	-		
Damp heat (steady state)		Exposed at 40±2°C, relative humidity 90 to 95%, 96h.			③ No damage, crack and loose parts.				×	_		
Damp heat,cyclic		Exposed at -10 to +65°C, relative humidity 90 to 96%, 10 cycles, total 240h.			 Contact resistance: 300mΩ MAX. Insulation resistance: 1MΩ MIN. (at high humidity) Insulation resistance: 50MΩ MIN. (at dry) No damage, crack and loose parts. 				×	_		
Dry heat		Exposed	Exposed at 85±2°C, 96h.			① Contact resistance: 300mΩ MAX.				×	-	
Cold			posed at -55±3°C, 96h.			② No damage, crack and loose parts.				×	-	
Sulphur dioxide [JIS C 60068-2-42]		relative h 25±5ppr	ed at 40±2°C, humidity 80±5%, opm for 96h.			① Contact resistance: 300mΩ MAX. ② No damage, crack and loose parts.				×	_	
Hydrogen sulphide [JIS C 60068-2-43]		relative h	d at 40±2°C, humidity 80±5%, ppm for 96h.			No evidence of corrosion which affects connector's operation.			×	_		
COUNT DESCRIPT		ESCRIPTIO	ON OF REVISIONS DESIG		DESIG	GNED		CHECKED		DATE		
REMARK						APPROVE					06. 07	
			cified refer to IEC 60512			DESIGNE		-+	YH. MICHIDA		06. 07	
llalar : : !!		-: :: ::									06. 07	
Unless otherwise specified, r						DRAWN		١			06. 06	
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			est			ELC-370587-9)				
$\Pi \square$			LOII TOATTON OFFICE			-		FH58-**S-0. 2SHW (99)			I	
		OSE ELECTRIC CO., LTD. CODE			CODE			CL580	Δ	1/2		

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
Solderability	Soldered at solder temperature 245±3°C, for immersion duration 3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	×	_				
Resistance to soldering heat	 Reflow soldering: peak tmp. 250°C MAX. reflow tmp. over 230°C within 60 sec. Soldering irons: tmp. 350±10°C for 5±1 sec. 	No case-deformation and loose contacts. (note 4)	×	_				

(note1)

This connector is back flip lock type, and top/bottom both contact points are available.

(note2)

Do not close the actuator before inserting FPC even after the connector is mounted onto a PCB.

Closing the actuator without FPC could make the contact gap smaller, which increases the FPC insertion force.

(note3)

If pull-up or pull-down force is exepected to be applied to the FPC, stabilize the FPC into PCB or other fixed components.

(note4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWIN	IG NO.	ELC-370587-99-00			
HR	SPECIFICATION SHEET		PART NO.	99)	9)			
1.0	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	Δ	2/2		